

S/N 09/733,289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiao-Chun Mu et al.

Examiner: DiLinh Nguyen

Serial No.: 09/733,289

Group Art Unit: 2814

Filed: December 8, 2000

Docket No.: 884.798US1

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Customer Number: 21186

RESPONSE UNDER 37 CFR § 1.111

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

This responds to the Office Action mailed on March 21, 2007. Please consider the remarks in connection with the above-identified patent application as follows.